

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	Method of Managing Wafer Defects				
<p>Application Number : Date : First Named Applicant: Hung-En Tai Confirmation Number: Attorney Docket Number: LKSP0051USA</p>					
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Winston Hsu Registered Number: 41,526	/Winston Hsu/				

Documents being submitted:	Files
us-power-of-attorney-grant	LKSP0051-0-A1-uspoat.xml us-power-of-attorney-grant.dtd us-power-of-attorney-grant.xsl
us-request	LKSP0051-0-A1-usrequ.xml us-request.dtd us-request.xsl
us-assignment	LKSP0051-0-A1-usassn.xml us-assignment.xsl us-assignment.dtd LKSP0051-0-A1ASS1.tif LKSP0051-0-A1ASS2.tif
us-declaration	LKSP0051-0-A1-usdecl.xml us-declaration.dtd us-declaration.xsl
us-fee-sheet	LKSP0051-0-A1-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-declaration	LKSP0051-0-A1DEC1.tif
us-declaration	LKSP0051-0-A1DEC2.tif
application-body	LKSP0051-0-A1-ABX.xml application-body.dtd Image1.tif Image2.tif Image3.tif isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isogr1.ent isogr2.ent isogr3.ent isogr4.ent isolat1.ent isolat2.ent isomfrk.ent isomopf.ent isomscr.ent isonum.ent isopub.ent isotech.ent mathml2.dtd mathml2-qname-1.mod mmlalias.ent

application-body-pdf-wrap	mmlextra.ent
abstract-pdf	soextblx.dtd
claims-pdf	us-application-body.xsl
description-pdf	wipo.ent
drawings-pdf	LKSP0051-0-A1-ABX-pdf-wrap.xml
	LKSP0051-0-A1-ABX-abst.pdf
	LKSP0051-0-A1-ABX-clms.pdf
	LKSP0051-0-A1-ABX-desc.pdf
	LKSP0051-0-A1-ABX-draw.pdf
Comments	